SN54BCT2244

SCBS017D - SEPTEMBER 1988 - REVISED MARCH 2003

J OB W PACKAGE

- Operating Voltage Range of 4.5 V to 5.5 V
- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- Output Ports Have Equivalent 33-Ω Series Resistors, So No External Resistors Are Required
- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers

description/ordering information

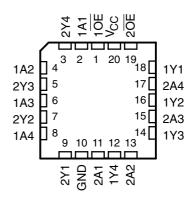
The 'BCT2244 devices are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the 'BCT2240 devices and SN74BCT2241, these devices provide the choice of selected combinations of inverting and noninverting outputs, symmetrical active-low output-enable (\overline{OE}) inputs, and complementary OE and \overline{OE} inputs. These devices feature high fan-out and improved fan-in.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The outputs, which are designed to source or sink up to 12 mA, include $33-\Omega$ series resistors to reduce overshoot and undershoot.

3N34DC122	44 0		WFACKAGE								
SN74BCT2244 DW, N, OR NS PACKAGE											
(TOP VIEW)											
1 <u>0</u> [1	20] v _{cc}								
1A1 [2	19	2 <u>0E</u>								
2Y4 [3	18] 1Y1								
1A2 [4	17] 2A4								
2Y3 [5	16] 1Y2								
1A3 [6	15] 2A3								
2Y2 [7	14] 1Y3								
1A4 [8	13] 2A2								
2Y1 [9	12] 1Y4								
GND [10	11] 2A1								

SN54BCT2244 ... FK PACKAGE (TOP VIEW)



T _A	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP – N	Tube	SN74BCT2244N	SN74BCT2244N		
000 10 7000		Tube	SN74BCT2244DW	DOTOOU		
0°C to 70°C	SOIC – DW	Tape and reel	SN74BCT2244DWR	BCT2244		
	SOP – NS	Tape and reel	SN74BCT2244NSR	BCT2244		
	CDIP – J	Tube	SNJ54BCT2244J	SNJ54BCT2244J		
–55°C to 125°C	CFP – W	Tube	SNJ54BCT2244W	SNJ54BCT2244W		
	LCCC – FK	Tube	SNJ54BCT2244FK	SNJ54BCT2244FK		

ORDERING INFORMATION

⁺ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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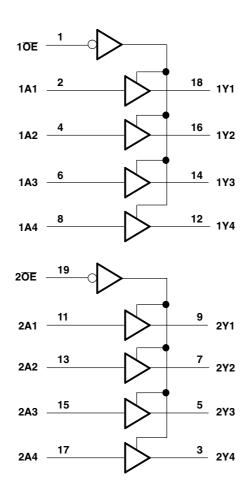


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SN54BCT2244, SN74BCT2244 **OCTAL BUFFÉRS AND LINE/MOS DRIVERS** WITH 3-STATE OUTPUTS SCBS017D - SEPTEMBER 1988 - REVISED MARCH 2003

FUNCTION TABLE (each buffer)								
INPU	JTS	OUTPUT						
ŌĒ	Α	Y						
L	Н	Н						
L	L	L						
Н	Х	Z						

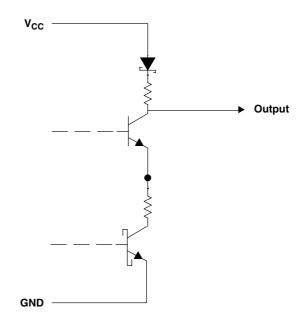
logic diagram (positive logic)





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schematic of Y outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input voltage range, V_I (see Note 1) Voltage range applied to any output in the disal Voltage range applied to any output in the high Input clamp current, I_{IK}	bled or power-off state, V_O state, V_O	-0.5 V to 7 V -0.5 V to 5.5 V -0.5 V to 5.5 V
Current into any output in the low state, I_O Package thermal impedance, θ_{JA} (see Note 2): Storage temperature range, T_{stg}	DW package N package NS package	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions(see Note 3)

		SI	154BCT2	244	SN			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			0.8			0.8	V
I _{IK}	Input clamp current			-18			-18	mA
I _{OH}	High-level output current			-12			-12	mA
I _{OL}	Low-level output current			12			12	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEGT CONDITIONS			54BCT22	244	SN7			
PARAMETER	IE	ST CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
V _{IK}	$V_{CC} = 4.5 V,$	l _l = –18 mA			-1.2			-1.2	V
N N		I _{OH} = -1 mA	2.4			2.4			v
V _{OH}	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2			2			v
V	V AEV	I _{OL} = 1 mA		0.15	0.5		0.15	0.5	v
V _{OL}	$V_{CC} = 4.5 V$	I _{OL} = 12 mA		0.35	0.8		0.35	0.8	v
lį	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
I _{IH}	$V_{CC} = 5.5 V,$	V _I = 2.7 V			20			20	μA
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.5 V			-1			-1	mA
I _{OZH}	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μA
I _{OZL}	V _{CC} = 5.5 V,	V _O = 0.5 V			-50			-50	μA
I _{OS} ‡	V _{CC} = 5.5 V,	V _O = 0	-100		-225	-100		-225	mA
I _{ССН}	V _{CC} = 5.5 V,	Outputs open		23	37		23	37	mA
I _{CCL}	V _{CC} = 5.5 V,	Outputs open		53	77		53	77	mA
I _{CCZ}	V _{CC} = 5.5 V,	Outputs open		6.5	10		6.5	10	mA
C _i	$V_{CC} = 5 V,$	V _I = 2.5 V or 0.5 V		6			6		pF
Co	$V_{CC} = 5 V,$	V_{O} = 2.5 V or 0.5 V		11			11		pF

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

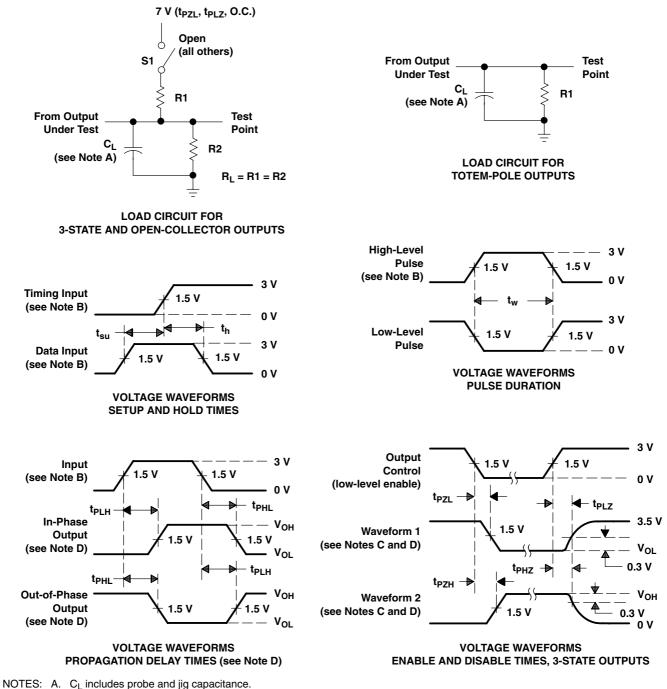
switching characteristics over recommended ranges of supply voltage and operating free-air	
temperature, C _L = 50 pF (unless otherwise noted) (see Figure 1)	

PARAMETER	FROM	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54BC	CT2244	SN74BC	UNIT	
	(INPUT)		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	•	V	0.5	3	4.4	0.5	5.2	0.5	4.9	
t _{PHL}	A	Ŷ	1.6	4.6	6.3	1.6	7.1	1.6	6.7	ns
t _{PZH}		Y	2.4	6.1	7.7	2.4	9.1	2.4	8.7	
t _{PZL}	ŌĒ		3.9	7.6	9.4	3.9	10.8	3.9	10.4	ns
t _{PHZ}	<u>AE</u>	V	1.7	5.2	6.9	1.7	8.1	1.7	7.8	20
t _{PLZ}	ŌĒ	Ŷ	2.8	6.5	8.3	2.8	10.9	2.8	9.8	ns

PARAMETER MEASUREMENT INFORMATION



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- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, t_r = t_f \leq 2.5 ns, duty cycle = 50%. C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.
- E. When measuring propagation delay times of 3-state outputs, switch S1 is open.
- F. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9074101M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9074101M2A SNJ54BCT 2244FK	Samples
5962-9074101MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9074101MR A SNJ54BCT2244J	Samples
SN74BCT2244DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT2244	Samples
SN74BCT2244N	ACTIVE	PDIP	Ν	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	0 to 70	SN74BCT2244N	Samples
SNJ54BCT2244FK	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9074101M2A SNJ54BCT 2244FK	Samples
SNJ54BCT2244J	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9074101MR A SNJ54BCT2244J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.



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PACKAGE OPTION ADDENDUM

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54BCT2244, SN74BCT2244 :

- Catalog : SN74BCT2244
- Military : SN54BCT2244

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-9074101M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
SN74BCT2244DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74BCT2244N	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54BCT2244FK	FK	LCCC	20	1	506.98	12.06	2030	NA

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW0020A



PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



DW0020A

EXAMPLE BOARD LAYOUT

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



DW0020A

EXAMPLE STENCIL DESIGN

SOIC - 2.65 mm max height

SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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